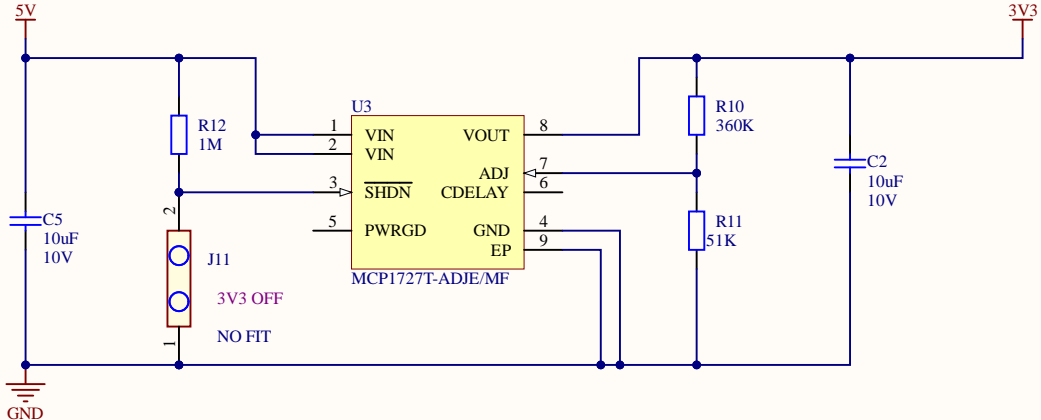
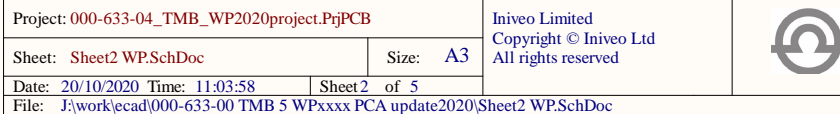
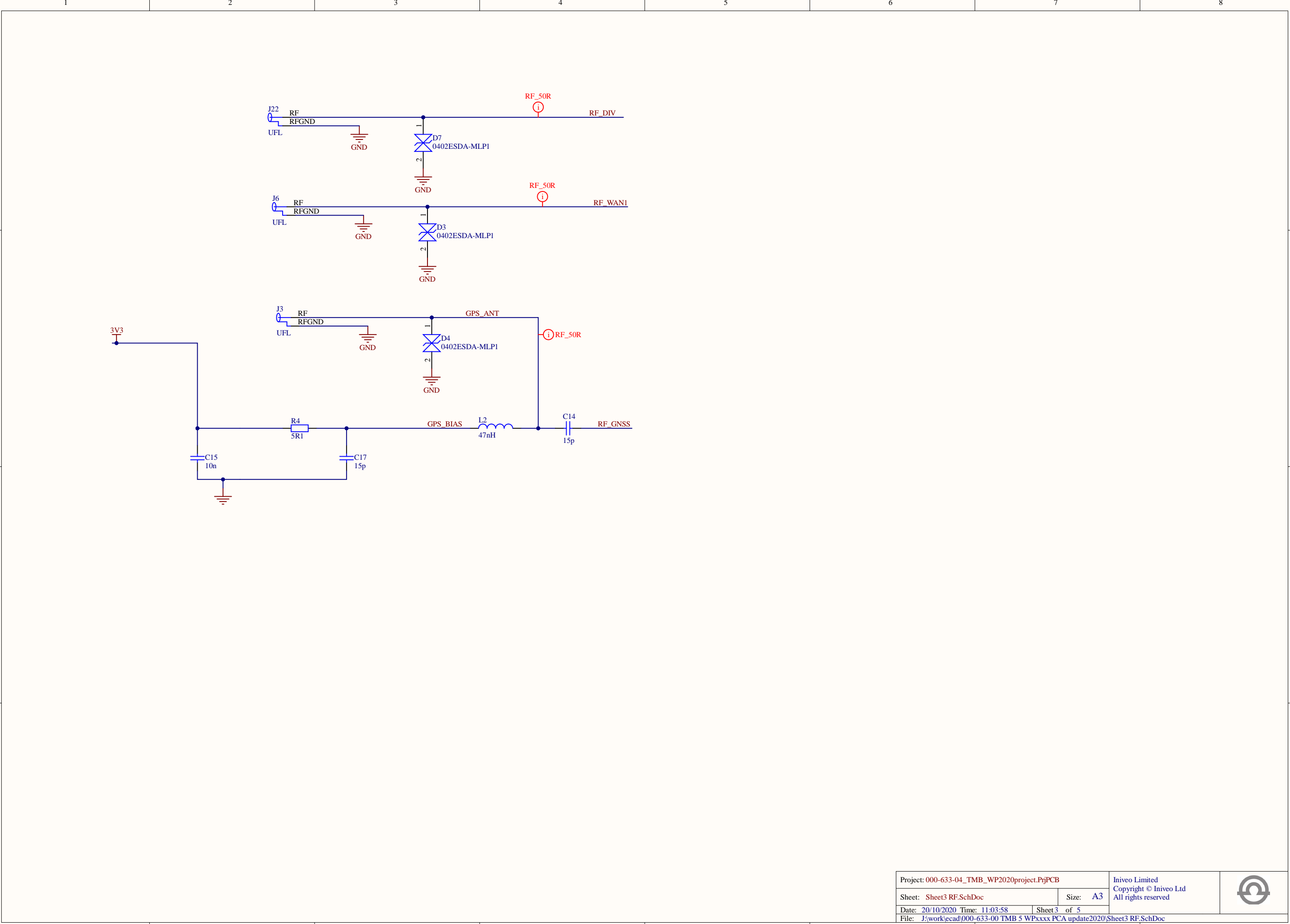
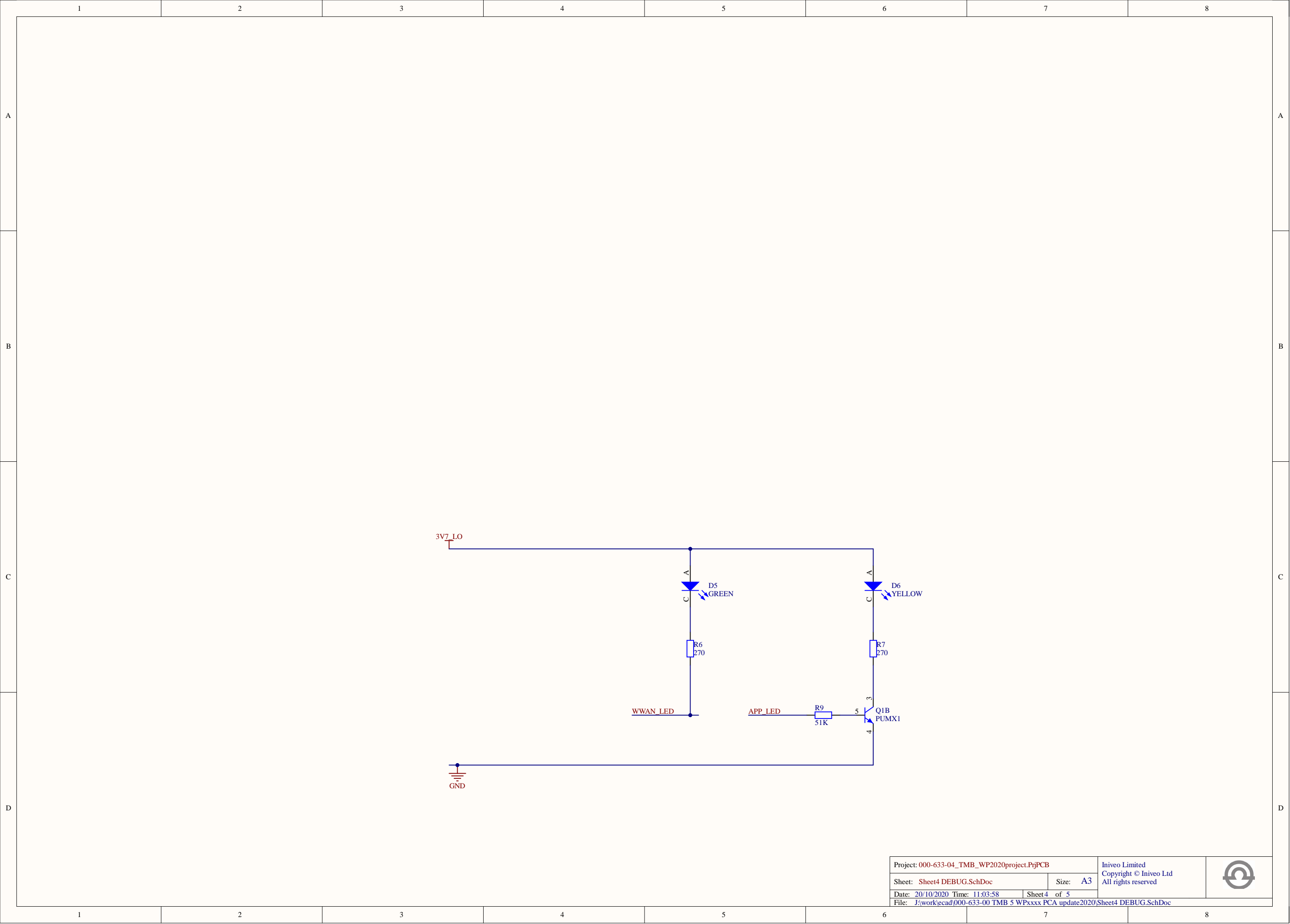


GND CONNECTION





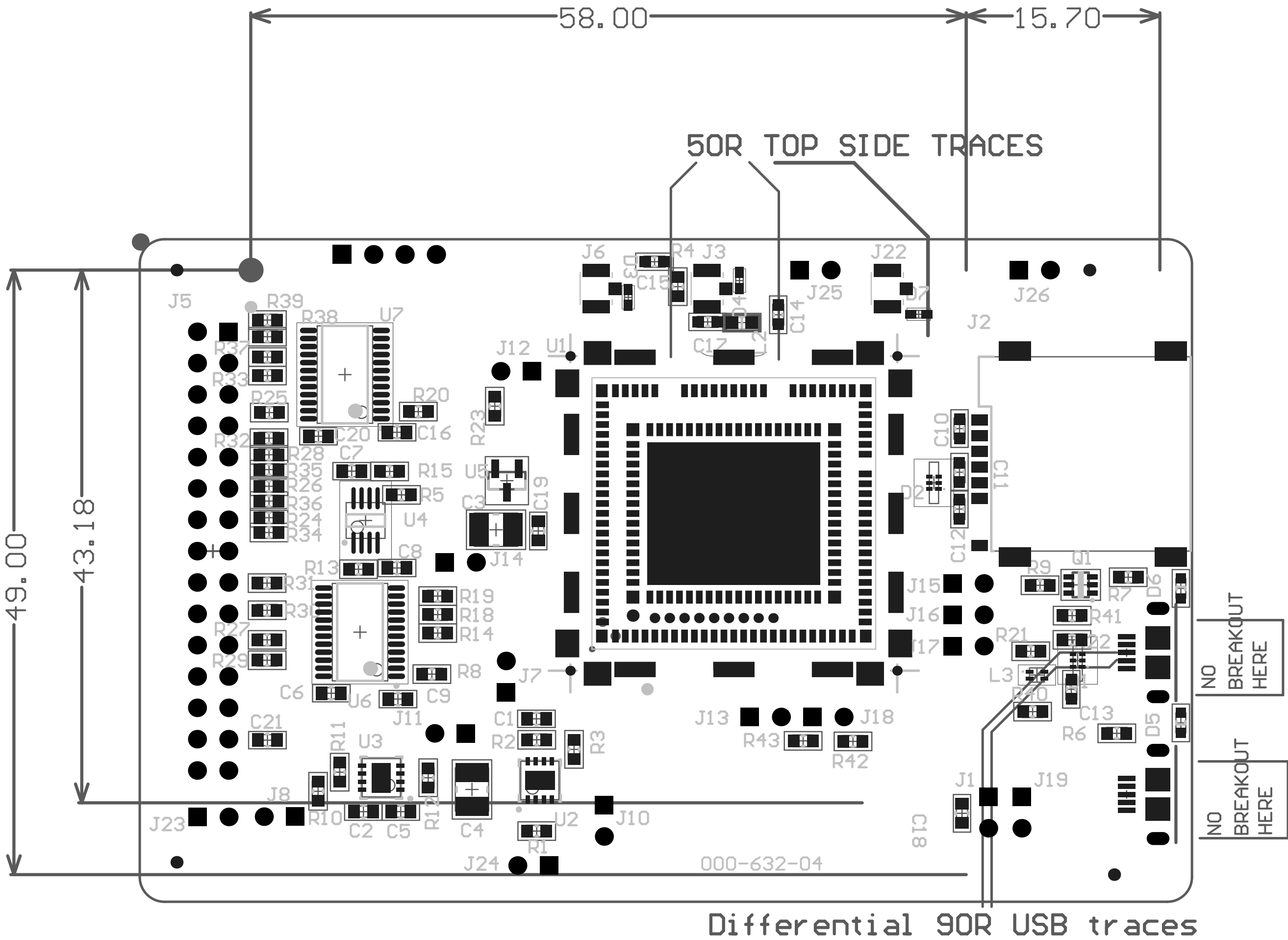






SUGGESTED BOARD STRUCTURE

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.010mm | 3.5 | |
| 1 | Top Layer | Copper | 0.018mm | | |
| | Dielectric1 | FR-4 | 0.360mm | 4.8 | |
| 2 | Mid-Layer 1 | Copper | 0.035mm | | |
| | Dielectric2 | FR-4 | 0.710mm | 4.8 | |
| 3 | Mid-Layer 2 | Copper | 0.035mm | | |
| | Dielectric3 | FR-4 | 0.360mm | 4.8 | |
| 4 | Bottom Layer | Copper | 0.018mm | | |
| | Bottom Solder | Solder Resist | 0.010mm | 3.5 | |
| | Bottom Overlay | | | | |



DIMENSIONS IN MM

FINISHED BOARD THICKNESS 1.6mm

COPPER WEIGHT min 1oz

BOARD IS FOUR LAYER

SOLDER MASK COLOUR BLACK**

SOLDER MASK EXPANSION HAS BEEN SET TO 0mm

PCB FABRICATOR WILL DEFINE THE FINAL VALUE SOLDER MASK EXPANSION

SILK SCREEN COLOUR IS YELLOW**

ALL MATERIAL MUST BE ROHS COMPLIANT

CORE MATERIAL FR4

BOARD FINISH GOLD**

BOARD HAS IMPEDANCE CONTROLLED TRACKS ON LAYER 1 and LAYER 3.

TOP LAYER = 1

MID1 LAYER = 2

MID2 LAYER = 3

BOT LAYER = 4

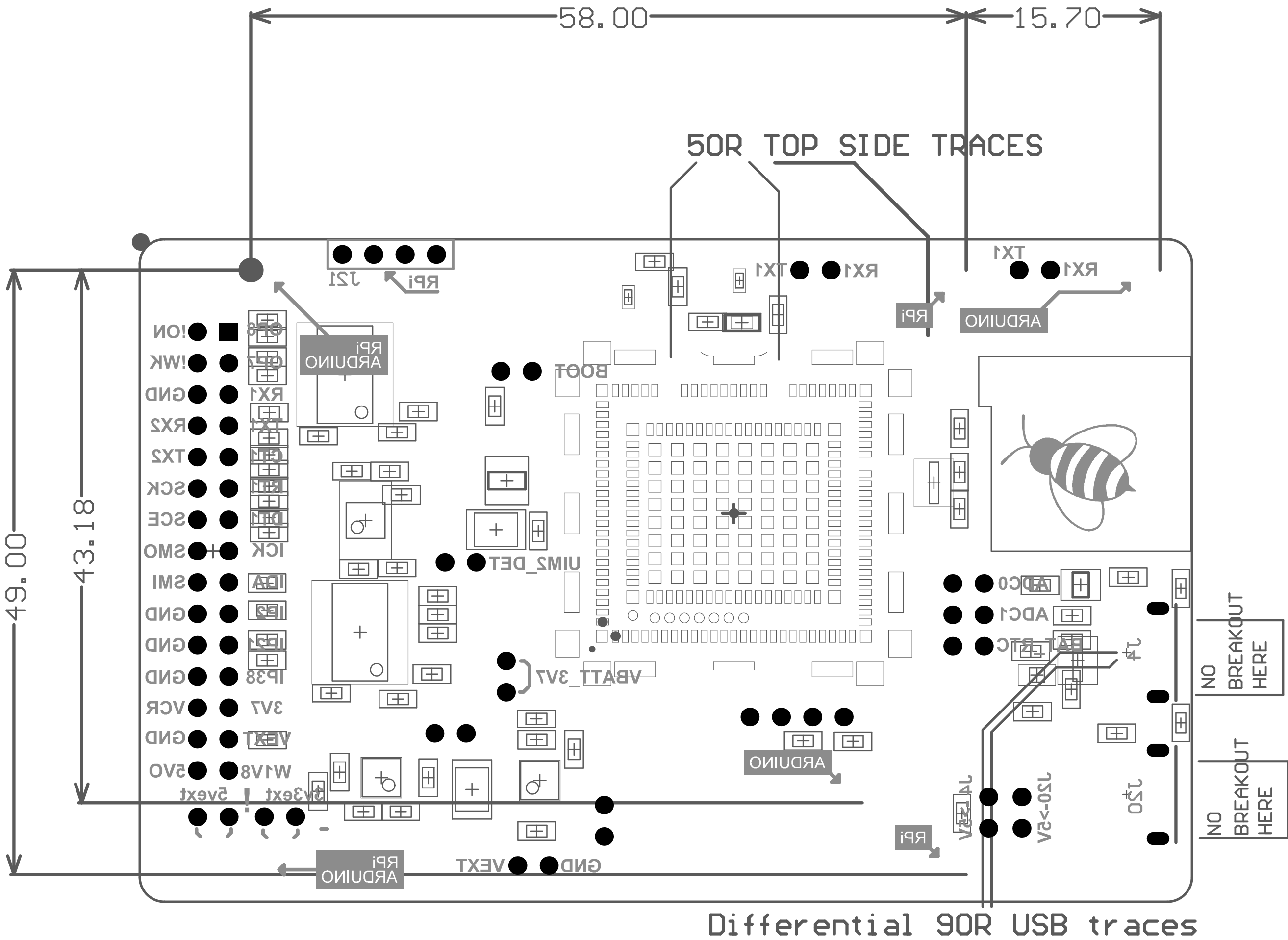
NOTE -

** FOR PROTOTYPES THE FABRICATOR CAN USE THEIR OWN DEFAULTS

| | | | | | |
|---------------|---------------|--|-----------|----------------|---------|
| ENGINEER: | JOHN THOMPSON | | TITLE: | TMB 5 | |
| PCB DESIGNER: | | | | | |
| DATE: | 20/10/2020 | | PART NO.: | PCB 000-632-02 | REV: 01 |
| FILE NAME: | | | DWG NO: | SCALE: | |

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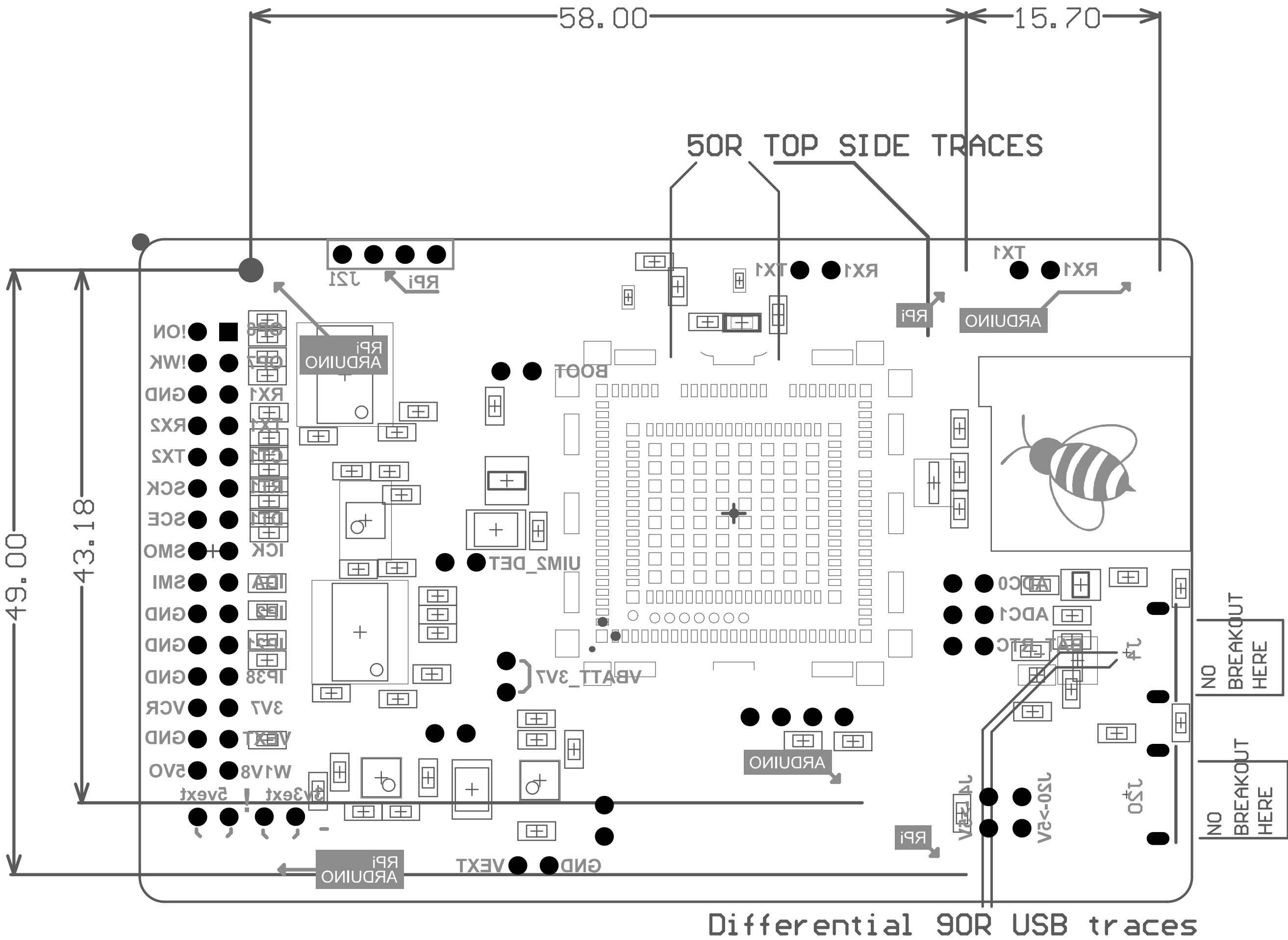
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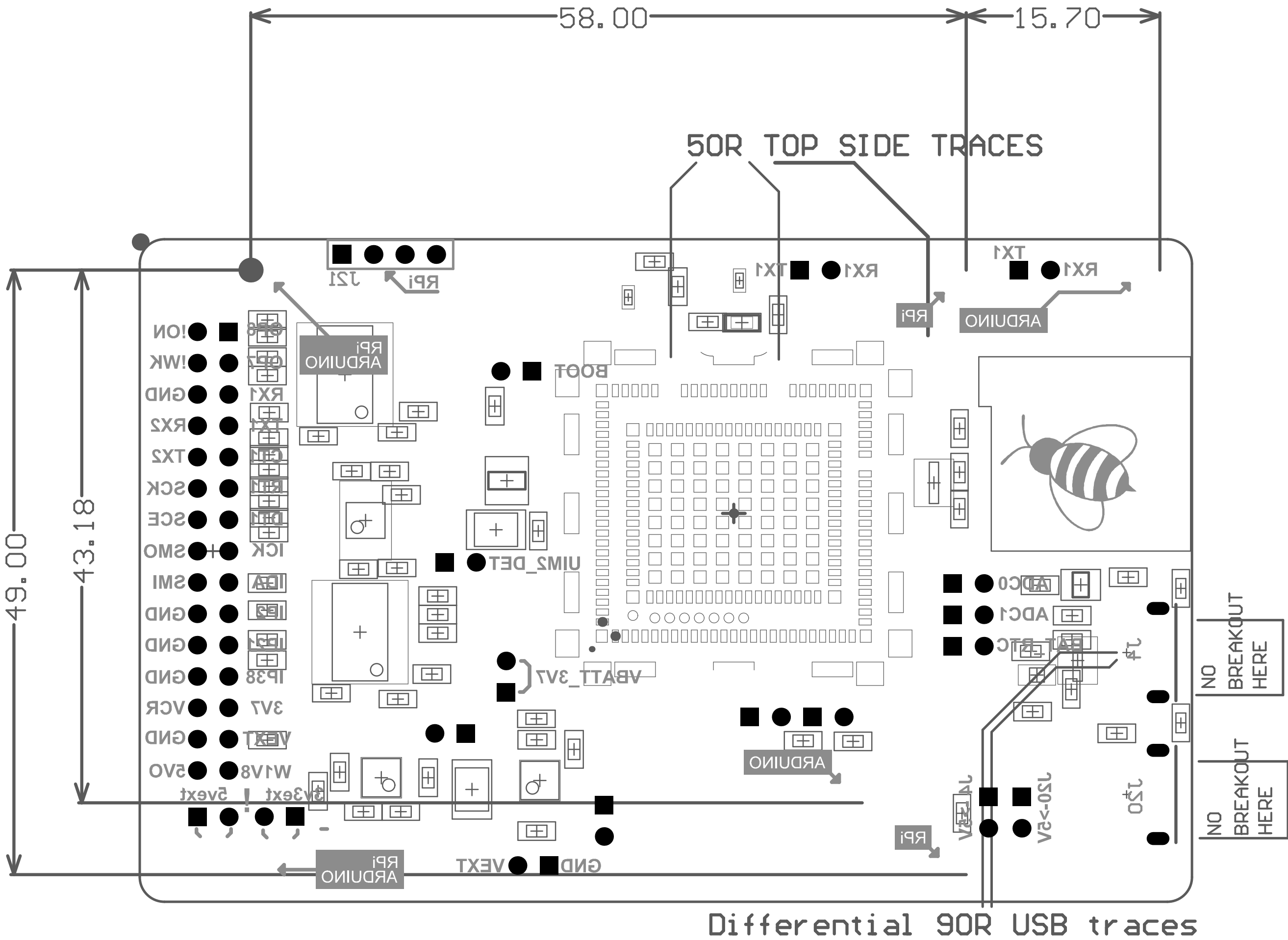
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